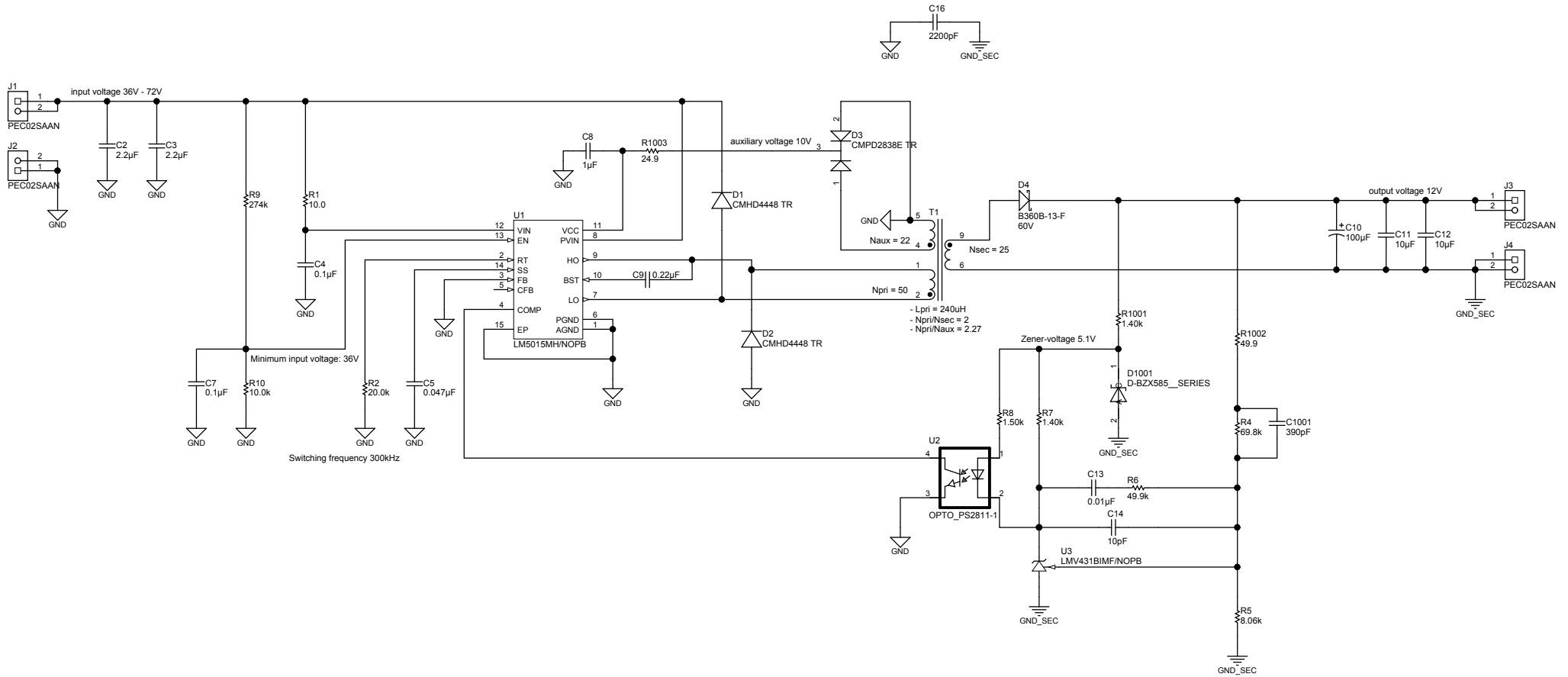


Notes:

- *Design was implemented on LM5015ISOEVAL-evaluation board.
- *D3 can be replaced with single diode.
- *R1002 is for test purposes only.
- *Components with designator 100x have no footprint on PCB.



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Designed for: Public Release		Mod. Date: 4/11/2014	
Project Title: Two-Switch Flyback, 12.0V @ 0.6A		Sheet Title:	
Number: PMP10037	Rev: A	Assembly Variant: Variant name not interpreted	Sheet: 1 of 1
SVN Rev: Not in version control		File: PMP10037RevA.SchDoc	Size: B
Drawn By: Juha Pesonen		Contact: http://www.ti.com/support	
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